



MICROCHIP™

MARKETING COMMUNICATION

Date: 8/14/01

Subject: Change Notice: 44 MQFP and 44/64/80 TQFP Assembly Site Qualification

From: John Helseth – PICmicro/SDP Marketing

Location: Chandler

To:	RSMs	FAMs	FAEs	RDMs	DSMs
CC:	P. Aguero	E. Alvarado	L. Donges	J. Barta	G. Bell
	T. Billington	R. Bosshardt	L. Boyd	M. Braun	P. Breault
	S. Caldwell	M. Campbell	D. Carlson	R. Cates	D. Chaffee
	D. Chu	R. Crist	S. D'Souza	E. Dias	R. Drwinga
	F. Duvenhage	J. Dysthe	J. Fernandez	S. Fink	D. Fisher
	W. Fitzgerald	D. Yeskey	E. Gholson	M. Gonzalez	D. Good
	J. Gutierrez	S. Vernier	B. Hollon	J. Hoxsie	L. Hubby
	D. Humphrey	K. Jackson	C. Keller	S. Kennelly	B. Kerick
	A. Kuzdas	D. Johansen	D. Lambert	I. Lao	M. Little
	A. Lovrich	G. Luke	K. Marneweck	S. Marsh	J. Medigovich
	S. Mitra	J. Oatley	M. Obolsky	R. Olson	G. Parnell
	J. Pepping	C. Popovich	G. Perzanowski	G. Rigg	G. Robinson
	L. Ross	C. Russell	S. Sanghi	W. Seitz	E. Sells
	B. Briggs	R. Simoncic	N. Smith	K. Stabler	S. Strickler
	KC Sun	H. Teeter	D. Termer	J. Thomsen	C. Trotto
	K. Verhoff	C. Wood	P. Whitelock	D. Zehrbach	J. Stelzer

Please notify customers of a change in the qualified assembly location for 44 MQFP (PQ Package) and 44/64/80 TQFP (PT Package) PICmicro devices.

In mid July 2001, Microchip will start shipping final assembly of the following PICmicro devices that were assembled at Carsem (S), Malaysia. These PICmicro devices are:

44 PIN:

PIC16C64A	PIC16C65A	PIC16C65B	PIC16CR65	PIC16C67	PIC16C74A	PIC16C74B
PIC16F74	PIC16C77	PIC16F77	PIC16C662	PIC16C774	PIC16C765	PIC16F871
PIC16F874	PIC16F877	PIC17C42A	PIC17CR42	PIC17C43	PIC17CR43	PIC17C44
PIC18C442	PIC18C452					

64 PIN:

PIC16C923	PIC16C924	PIC16C925	PIC16C926	PIC17C752	PIC17C756A	PIC18C601
PIC18C658						

80 PIN:

PIC17C762	PIC17C766	PIC18C858	PIC18C801
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This effects ALL temperature ranges, ALL speeds and ALL oscillator selections of the listed PICmicro devices.

All packages will be Tin/Lead (SnPb) solder plated leadframes with solder plating being accomplished at Carsem. Both packages (MQFP and TQFP) will be MP8000 molding compound with laser marking.

This is classified as a **CHANGE** (customers need to be notified). Please review your customer base that currently require notification for the PICmicro devices and notify them of the Carsem assembly facility changes. Please contact either your PICmicro/SDP Product Marketing Manager, your Regional Account Representative or Automotive Marketing Manager and let them know which customers will require qualification before shipments commence.

This change notice **will be posted** to the Microchip Customer Notification portion of the Microchip web site.

Thank you for your assistance and understanding during this change.

CHANGE IMPLEMENTATION NOTICE

CCB #: 311 & 312

Notice #: _____

The information shown below reflects a change that is being implemented. Please review the data and inform those customers that require 'Change Notification'

Customer Name: Per cover letter Microchip Part # (New):
Customer Part #: 44 MQFP & 44/64/80 TQFP Packages Microchip Part # (Old):
Projected Ship Date of Revised Device: 7/15/01

Description of Change: Qualification and Production loading of Carsem, Malaysia assembly site for 44 MQFP (CCB #311) & 44/64/80 TQFP (CCB #312) packages with laser marking using MP8000 molding compound and SnPb solder plate lead-frame.
Impacts to Data Sheet: None
Reason for Change: In order to reduce the process cycle time for PICmicro devices, Microchip has qualified assembly capability at Carsem, Malaysia.
Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)
None other than Traceability marking

Summary of Qualification Results: (Reference Report Number if applicable):
Full Qualification reports available upon request. Please reference document numbers #Q02004 (CCB # 311) and Q2005 (CCB #312) when requesting this information.
Note: Request for this report shall be made through CHANDLER DOCUMENT CONTROL
Additional Comments:
Requires customer approval status within 3 working weeks.

Customer Approval: YES NO
Signature: _____ Date: _____
Name: _____ (Please Print)
Company Name: _____ Location: _____ (Please Print)

Do you wish to receive future change notices via E-mail ONLY? YES NO
Signature: _____
The Electronic Notice option is being provided to prevent notification delays due to postal issues. E-mail Address : _____
By selecting this option, you will receive an electronic version of this form at the time of Change Notice issue. You will need to print, sign and fax your approval to 480-792-7277

NOTE: If we do not receive your reply by "DATE", we will consider that you have accepted this change.

RECOMMENDED CUSTOMER COVER LETTER for LIMITED DISTRIBUTION

Date:
From:
To:

Subject: Change Implementation Notice #

Dear Customer:

The following notice is to communicate a change that is being implemented on part number: _____. Please review the supporting data, which includes a description of the change, the reasons for the change, and a projected shipment date (pending your approval of the change).

If you are not the proper person to receive this Change Notice, please forward this to the appropriate party in your organization and notify us so that we can update our records. If you wish to receive future Change Notices via email only, please check the appropriate box on the Change Notice form and sign.

Once you have reviewed the information, please indicate your approval by signing the attached change notification and return to Microchip Technology at it's corporate location, by fax or through email. If we do not receive your reply by **MM/DD/YY**, we will consider your non-reply as acceptance of this change.

Address: Microchip Technology, Inc.
2355 West Chandler Blvd.
Chandler, AZ 85224-6199

Attention: Customer Service

Fax Number: (480) 792-7277

Email: cn@microchip.com

Very Truly Yours,
Headquarter Sales Customer Service

RECOMMENDED CUSTOMER COVER LETTER for MASS DISTRIBUTION

Date:
From:
To:

Subject: Change Implementation Notice #

Dear Customer,

The following notice is to communicate a change that is being implemented on the various **Products** listed on the attached Change Notice. Please review the supporting data, which includes a description of the change, the reasons for the change, and a projected shipment date (pending your approval of the change). Should you have any questions regarding this notification, please contact your local sales representative.

If you are not the proper person to receive this Change Notice, please forward this to the appropriate party in your organization and notify us so that we can update our records. If you wish to receive future Change Notices via email only, please check the appropriate box on the Change Notice form and sign.

Once you have reviewed the information, please indicate your approval by signing the attached change notification and return to Microchip Technology at it's corporate location, by fax or through email. If we do not receive your reply by **MM/DD/YY**, we will consider your non-reply as acceptance of this change.

Address: Microchip Technology, Inc.
2355 West Chandler Blvd.
Chandler, AZ 85224-6199

Attention: Customer Service

Fax Number: (480) 792-7277

Email: cn@microchip.com

Very Truly Yours,
Headquarter Sales Customer Service